

WHAT IS CLAIMED IS:

1. A holder for restraining and electrically grounding a component during a wire bonding process, said holder comprising:
 - an electrical ground;
 - a rigid pedestal; and
 - a conductive resilient member supported by said rigid pedestal and electrically connected to said electrical ground, said conductive resilient member operable to engage electrical contacts on said component electrically connecting said contacts with said electrical ground.
2. The holder of Claim 1, said rigid pedestal further comprising a vacuum cavity, said vacuum cavity operable to hold said component against said rigid pedestal.
3. The holder of Claim 1, said conductive resilient member further comprising a first face operable to engage said electrical contacts, said first face extending beyond adjacent portions of said rigid pedestal.
4. The holder of Claim 3, said conductive resilient member operable to deform as said component is pressed against said conductive resilient member such that said component contacts said adjacent portions of said rigid pedestal.
5. The holder of Claim 1, wherein said component is grounded through said conductive resilient member and said pedestal.
6. The holder of Claim 1, wherein said conductive resilient member is a silicone elastomer.
7. The holder of Claim 1, wherein said conductive resilient member is a silicone elastomer impregnated with a metal.

8. The holder of Claim 1, wherein said conductive resilient member is a Ag-Cu filled silicone elastomer.

an electrical ground;

a capillary tube holding a portion of said bond wire;

an arm attached to said capillary tube for pressing said wire held in said tube against bond pads on a device and package; and

a rigid pedestal for supporting said device and package, said rigid pedestal comprising a conductive resilient member electrically connected to said electrical ground operable to engage electrical contacts on said package and electrically connect said contacts to said electrical ground.

10. The wirebond machine of Claim 9, wherein said conductive resilient member is a silicone elastomer.

11. The wirebond machine of Claim 9, wherein said conductive resilient member is a silicone elastomer impregnated with a metal.

12. The wirebond machine of Claim 9, wherein said conductive resilient member is a Ag-Cu filled silicone elastomer.

13. A method of attaching bond wires to a semiconductor device and package, the method comprising the steps of:

providing an electrically ground;

providing a rigid pedestal having a vacuum cavity and at least one conductive resilient member on a surface of said rigid pedestal;

placing a component on said surface, said component comprised of a package and an electrical device inside said package;

holding said component against said surface using a vacuum applied to said vacuum cavity to form a ground connect between said component and said conductive resilient member;

attaching a bond wire to a bond pad on said package and a bond pad on said electrical device inside said package.

14. The method of Claim 13, said step of providing a rigid pedestal further comprising the step of providing a rigid pedestal having at least one conductive resilient member comprised of an elastomer on a surface of said rigid pedestal.
15. The method of Claim 13, said step of providing a rigid pedestal further comprising the step of providing a rigid pedestal having at least one conductive resilient member comprised of a silicone elastomer on a surface of said rigid pedestal.
16. The method of Claim 13, said step of providing a rigid pedestal further comprising the step of providing a rigid pedestal having at least one conductive resilient member comprised of a metal impregnated silicone elastomer on a surface of said rigid pedestal.
17. The method of Claim 13, said step of providing a rigid pedestal further comprising the step of providing a rigid pedestal having at least one conductive resilient member comprised of a Ag-Cu filled elastomer on a surface of said rigid pedestal.

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